

ABSTRACT OF THE INVENTION

A semiconductor assembly and method has channels formed in a leadframe. The channels act as a lock between the leadframe and a mold compound when the mold compound flows into the channels and congeals during the encapsulation process. The semiconductor assembly and method may further have a plurality of raised areas on the leadframe which are used for wirebonds. The raised areas allow the mold compound to get underneath the wirebonds and capture the wirebonds when the mold compound congeals during the encapsulation process.